

Full Wafer & Singulated Die / Module Test System

High Power Test and Reliability Verification Solution for Logic / Memory / Photonic Devices



SYSTEM BENEFITS

- **High Throughput Reliability Verification and Test System for Volume Production**
 - ◆ Handles full wafers / panels / singulated die / modules for highest production throughput
 - ◆ Identifies failing logic / memory / photonic die before final package integration
 - ◆ High power system with up to 18 Blades (slots) for wafer or panel testing using WaferPakTM contactors or 9 Blade capability for singulated die / module DiePak[®] carriers
- **Configurable Channel Resources**
 - ◆ Multiple resource modules available per Blade (slot): Universal Channel Modules, High Voltage Channel Modules or High Current Channel Modules
 - ◆ Up to 2,048 "Universal Channel" resources: (I/O / Clock / PPMU / DPS) per Blade with deep scan, pattern data and capture memory per channel for test of devices with BIST/DFT
 - ◆ Up to 1,024 high voltage (29V) or high current (2A) sources resources per Blade
- **Production Proven Full-Wafer Reliability Verification & Test Solution**
 - ◆ Reduces test costs by functionally testing wafers/die/modules during reliability verification
 - ◆ Offers a total solution when configured with a WaferPak contactor / DiePak carrier and Wafer Aligner / DiePak Loader
 - ◆ Protects devices with individual per channel over-current and over-voltage protection

"Setting the Test Standard for Tomorrow"

CORPORATE HEADQUARTERS

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